

**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q79041

Youichi KUKIMOTO, et al.

Appln. No.: 10/765,931

Group Art Unit: 2823

Confirmation No.: 1863

Examiner: Khiem D. NGUYEN

Filed: January 29, 2004

For: SOLDER DISPOSITION METHOD AND SOLDER BUMP FORMING METHOD

**EXCESS CLAIM FEE PAYMENT LETTER**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

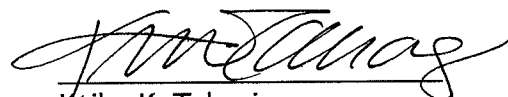
Sir:

An Amendment Under 37 C.F.R. § 1.111 is attached hereto for concurrent filing in the above-identified application. The resulting excess claim fee has been calculated as shown below:

	After Amendment		Highest No. Previously Paid For					
All Claims	25	-	20	=	5	X	\$50.00	= \$250.00
Independent	6	-	4	=	2	X	\$210.00	= \$420.00
					<b>TOTAL</b>			<b>= \$670.00</b>

The statutory fee of \$670.00 is charged to Deposit Account No. 19-4880. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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WASHINGTON OFFICE

**23373**

CUSTOMER NUMBER

Date: February 14, 2008